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FROM: Dennis Carleton**Telephone #:** 412-562-1893**Date:** 11/16/01**Additional Comments or Instructions:**The attached is confirmation that the Response and Amendment for
Serial No. 09/583,386 was mailed October 26, 2001.**Return Originals to:** Vicki Cremonese**Floor No.** 22D42053 / 0000021069

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386		Filing Date: 05/30/00	BIPC File No.: 000265
<p>REPORTING OF MEMS STRUCTURE IN SEALED CAVITY USING</p> <p>_____</p> <p>Date: 10/26/01</p>			
<p>Resolved:</p> <p>_____</p> <p>(including claims & abstract)</p> <p>_____ or □ Designation Sheet</p> <p>_____ Sheet(s)/Figs. _____ to _____</p> <p>_____ Document</p> <p>_____ Declaration</p> <p>_____ & Conveyance Cover Sheet</p> <p>_____ Information Disclosure Statement</p> <p>PTO 1449</p> <p>_____ Amendment</p> <p>_____ or Declaration</p> <p>_____ Fee</p>		<p><input type="checkbox"/> TM Application <input type="checkbox"/> ITU Basis</p> <p><input type="checkbox"/> Statement of Use</p> <p><input type="checkbox"/> Extension of Time</p> <p><input type="checkbox"/> Notice of Appeal</p> <p><input type="checkbox"/> Brief</p> <p><input type="checkbox"/> Petition</p> <p><input type="checkbox"/> Status Request</p> <p><input type="checkbox"/> Issue Fee</p> <p><input type="checkbox"/> Application for Renewal</p> <p><input type="checkbox"/> Specimen _____</p> <p><input type="checkbox"/> Certificate of Mailing</p> <p><input type="checkbox"/> Express Mail No. _____</p>	
<p>Response to Amendment</p> <p>No. _____ for \$ _____</p> <p>DNC/cle</p>		<p>PTO STAMP</p>	

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I hereby certify that this correspondence, being deposited with the United States Postal Service as first class mail in an envelope addressed to:

Assistant Commissioner for Patents
Washington, D.C. 20231

Oct. 26, 2001

Tamy Syer

#7/B
11-17-01
Harrison

PATENT
Attorney Docket No.: 000265

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: L. Richard Carley)

Serial No.: 09/583,386)

Filing Date: May 30, 2000)

) **Examiner:** Erik Kielin

) **Art Unit:** 2813

Entitled: MANUFACTURING OF MEMS STRUCTURE IN SEALED CAVITY USING
DRY-RELEASE MEMS DEVICE ENCAPSULATION

RESPONSE AND AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

This communication is being filed in response to the Notice of Non-Compliant Amendment dated October 19, 2001 in the above-referenced U.S. patent application.

The Applicant requests the entry of the following Amendments:

In the Specification:

- On page 3, please delete the third full paragraph and replace it with the following paragraph:

β^1 Figures 1A and 1B show a top view and a side cross-sectional view respectively of the silicon CMOS wafer used as the base of the MEMS micro-encapsulated structure.

- On page 3, please delete the fourth full paragraph and replace it with the following paragraph:

β^2 Figures 2A and 2B show a top view and a cross-sectional view respectively of the wafer of the Figure 1A with a sacrificial layer deposited thereon.